

Lead-Free Hot Air Reflow Soldering System

This lead-free hot air reflow system solders electronic components onto printed circuit boards (PCBs). It uses a hot air convection method to precisely control the temperature profile during the reflow process, ensuring optimal solder joint quality.



Overview

Professional Lead-Free Hot Air Reflow System

The ARL850U is a high-precision hot air reflow soldering system engineered for the assembly of electronic components onto printed circuit boards. Utilizing advanced hot air convection technology, it provides precise control over thermal profiles to ensure high-integrity solder joints. This system is specifically optimized for lead-free soldering processes, making it a reliable and efficient choice for demanding Surface Mount Technology (SMT) applications.

Technical Specifications

Soldering Method	Hot air convection
Application Compatibility	SMT, Lead-free Soldering, PCB Assembly
Model ID	ARL850U